



Process Change Notification

Aug-22-2018

Title: MCC Will Use Glass Passivated Chip For GS1AE~GS1ME Series Rectifiers

PCN#: 082218-1

Planned Effective Date :Nov-22-2018

Reliability Data: Available per individual request

Samples contact: Sales@mccsemi.com

For question concerning this notification: techsupport@mccsemi.com

Notification Type:

Final Process/Product Change Notification(FPCN)

MCC will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact techsupport@mccsemi.com



Micro Commercial Components®

130 W Cochran St, Unit B
Simi Valley, CA 93065
Tel:818-701-4933

Description and purpose :

To be more environment friendly and provide more robust parts to our customers, MCC will use glass passivated chip (GPP) to replace OJ chip (Open Junction) for GS1AE~GS1ME series rectifiers. GPP structure is more reliable and has better performances than OJ structure, internal qualification process had been finished and the report is available by individual request. MCC will use lead frame structure for GPP die and will assign new pn# to distinguish OJ products(see next page for details).

For any concern about this PCN, please feel free to contact your local sales representative or us directly via above E-mail address.

Qualification Data and Summary:

Devices were selected with 1000V voltage rating.

Qualification Test Result:

Test	Condition	Interval	Results
HTRB	Tj=150°C, 80% Vr,	1000 Hrs	0/77
OP	Ta=25°C, Rated If,	1000 Hrs	0/77
PCT	Ta=121°C, 100%RH, 15psig	96 Hrs	0/77
TC	-55°C~+150°C	1000 Cycles	0/77
Resistance to solder heat	260°C for 10s		0/10
Solderability	245°C for 5s		0/10



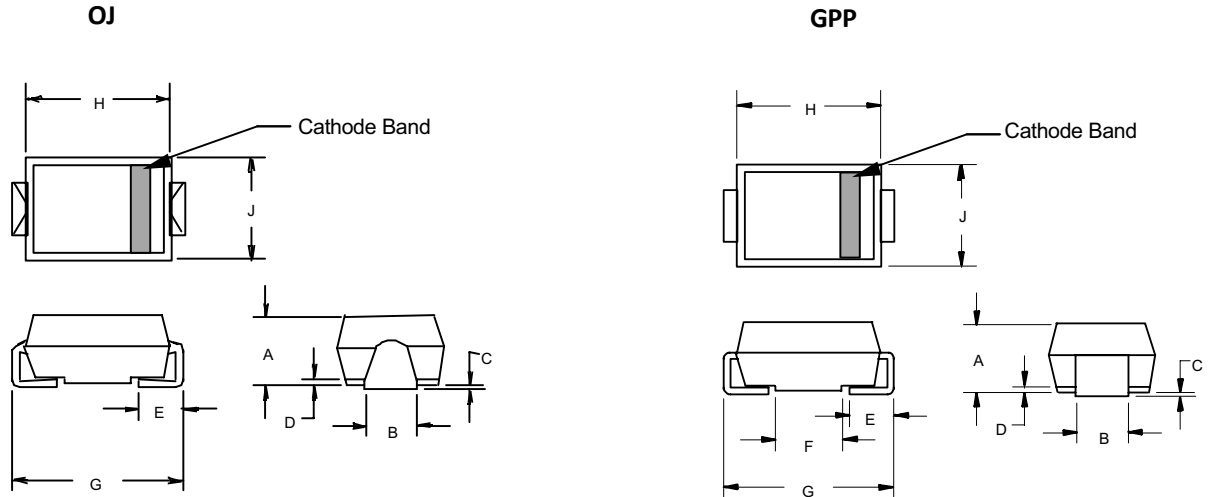
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Comparison between OJ and GPP part appearance



DIM	DIMENSIONS				NOTE
	INCHES		MM		
	MIN	MAX	MIN	MAX	
A	.079	.096	2.01	2.44	
B	.011	.017	0.28	0.43	
C	.002	.008	.05	.20	
D	---	.02	---	.51	
E	.030	.060	.76	1.52	
G	.189	.208	4.80	5.30	
H	.157	.180	4.00	4.57	
J	.090	.115	2.29	2.92	

DIM	DIMENSIONS				NOTE
	INCHES		MM		
	MIN	MAX	MIN	MAX	
A	.079	.096	2.00	2.44	
B	.050	.064	1.27	1.63	
C	---	.006	---	.15	
D	---	.02	---	.51	
E	.030	.060	.76	1.52	
F	.065	.091	1.65	2.32	
G	.189	.220	4.80	5.59	
H	.157	.181	4.00	4.60	
J	.090	.115	2.25	2.92	

Affected Pn#(OJ Die)	New Pn#(GPP Die)
GS1AE-TP	GS1A-LTP
GS1BE-TP	GS1B-LTP
GS1DE-TP	GS1D-LTP
GS1JE-TP	GS1J-LTP
GS1KE-TP	GS1K-LTP
GS1ME-TP	GS1M-LTP